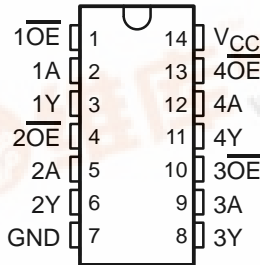# SN54AHCT125, SN74AHCT125
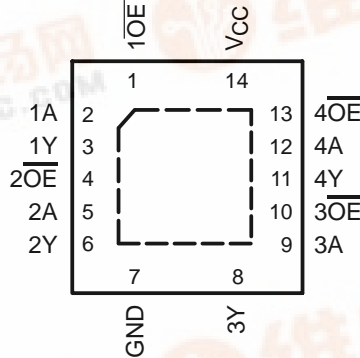## QUADRUPLE BUS BUFFER GATES
WITH 3-STATE OUTPUTS

SCLS264O – DECEMBER 1995 – REVISED JULY 2003

- **Inputs Are TTL-Voltage Compatible**
- **Latch-Up Performance Exceeds 250 mA Per JESD 17**

- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
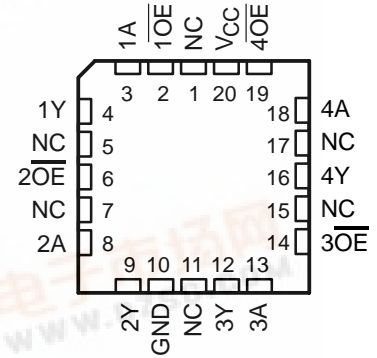 - **1000-V Charged-Device Model (C101)**

SN54AHCT125 . . . J OR W PACKAGE
SN74AHCT125 . . . D, DB, DGV, N, NS, OR PW PACKAGE
(TOP VIEW)

1OE	1	14	V$_{CC}$
1A	2	13	4OE
1Y	3	12	4A
2OE	4	11	4Y
2A	5	10	3OE
2Y	6	9	3A
GND	7	8	3Y

SN74AHCT125 . . . RGY PACKAGE
(TOP VIEW)

SN54AHCT125 . . . FK PACKAGE
(TOP VIEW)

NC – No internal connection

description/ordering information

The 'AHCT125 devices are quadruple bus buffer gates featuring independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable (OE) input is high. When OE is low, the respective gate passes the data from the A input to its Y output.

To ensure the high-impedance state during power up or power down, OE should be tied to V$_{CC}$ through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

T$_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Tape and reel	SN74AHCT125RGYR	HB125
	PDIP – N	Tube	SN74AHCT125N	SN74AHCT125N
	SOIC – D	Tube	SN74AHCT125D	AHCT125
		Tape and reel	SN74AHCT125DR	
	SOP – NS	Tape and reel	SN74AHCT125NSR	AHCT125
	SSOP – DB	Tape and reel	SN74AHCT125DBR	HB125
	TSSOP – PW	Tube	SN74AHCT125PW	HB125
		Tape and reel	SN74AHCT125PWR	
	TVSOP – DGV	Tape and reel	SN74AHCT125DGVR	HB125
–55°C to 125°C	CDIP – J	Tube	SNJ54AHCT125J	SNJ54AHCT125J
	CFP – W	Tube	SNJ54AHCT125W	SNJ54AHCT125W
	LCCC – FK	Tube	SNJ54AHCT125FK	SNJ54AHCT125FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TEXAS INSTRUMENTS

FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

logic diagram (positive logic)

Pin numbers shown are for the D, DB, DGV, J, N, NS, PW, RGY, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . –0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . –0.5 V to 7 V
Output voltage range, V_O (see Note 1) . . . . –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$) . . . . –20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) . . . . ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) . . . . ±25 mA
Continuous current through V_{CC} or GND . . . . ±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package . . . . 86°C/W
     (see Note 2): DB package . . . . 96°C/W
     (see Note 2): DGV package . . . . 127°C/W
     (see Note 2): N package . . . . 80°C/W
     (see Note 2): NS package . . . . 76°C/W
     (see Note 2): PW package . . . . 113°C/W
     (see Note 3): RGY package . . . . 47°C/W
Storage temperature range, T_{stg} . . . . –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
       2. The package thermal impedance is calculated in accordance with JESD 51-7.
       3. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 4)

		SN54AHCT125		SN74AHCT125		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	5.5	0	5.5	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–8		–8	mA
I_{OL}	Low-level output current		8		8	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		20		20	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

TEXAS
INSTRUMENTS

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	$T_A = 25°C$			SN54AHCT125		SN74AHCT125		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		$I_{OH} = -50$ μA	4.5 V	4.4	4.5		4.4		4.4		V
		$I_{OH} = -8$ mA		3.94			3.8		3.8		
V_{OL}		$I_{OL} = 50$ μA	4.5 V			0.1		0.1		0.1	V
		$I_{OL} = 8$ mA				0.36		0.44		0.44	
I_I		$V_I = 5.5$ V or GND	0 V to 5.5 V			±0.1		±1*		±1	μA
I_{OZ}		$V_O = V_{CC}$ or GND	5.5 V			±0.25		±2.5		±2.5	μA
I_{CC}		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		20		20	μA
ΔI_{CC}†		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			1.35		1.5		1.5	mA
C_i		$V_I = V_{CC}$ or GND	5 V		4	10				10	pF
C_o		$V_O = V_{CC}$ or GND	5 V		15						pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0$ V.
† This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 5$ V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25°C$			SN54AHCT125		SN74AHCT125		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	$C_L = 15$ pF		3.8**	5.5**	1**	6.5**	1	6.5	ns
t_{PHL}					3.8**	5.5**	1**	6.5**	1	6.5	
t_{PZH}	$\overline{OE}$	Y	$C_L = 15$ pF		3.6**	5.1**	1**	6**	1	6	ns
t_{PZL}					3.6**	5.1**	1**	6**	1	6	
t_{PHZ}	OE	Y	$C_L = 15$ pF		4.6**	6.8**	1**	8**	1	8	ns
t_{PLZ}					4.6**	6.8**	1**	8**	1	8	
t_{PLH}	A	Y	$C_L = 50$ pF		5.3	7.5	1	8.5	1	8.5	ns
t_{PHL}					5.3	7.5	1	8.5	1	8.5	
t_{PZH}	$\overline{OE}$	Y	$C_L = 50$ pF		5.1	7.1	1	8	1	8	ns
t_{PZL}					5.1	7.1	1	8	1	8	
t_{PHZ}	$\overline{OE}$	Y	$C_L = 50$ pF		6.1	8.8	1	10	1	10	ns
t_{PLZ}					6.1	8.8	1	10	1	10	
$t_{sk(o)}$			$C_L = 50$ pF			1***				1	ns

** On products compliant to MIL-PRF-38535, this parameter is not production tested.
*** On products compliant to MIL-PRF-38535, this parameter does not apply.

noise characteristics, $V_{CC} = 5$ V, $C_L = 50$ pF, $T_A = 25°C$ (see Note 5)

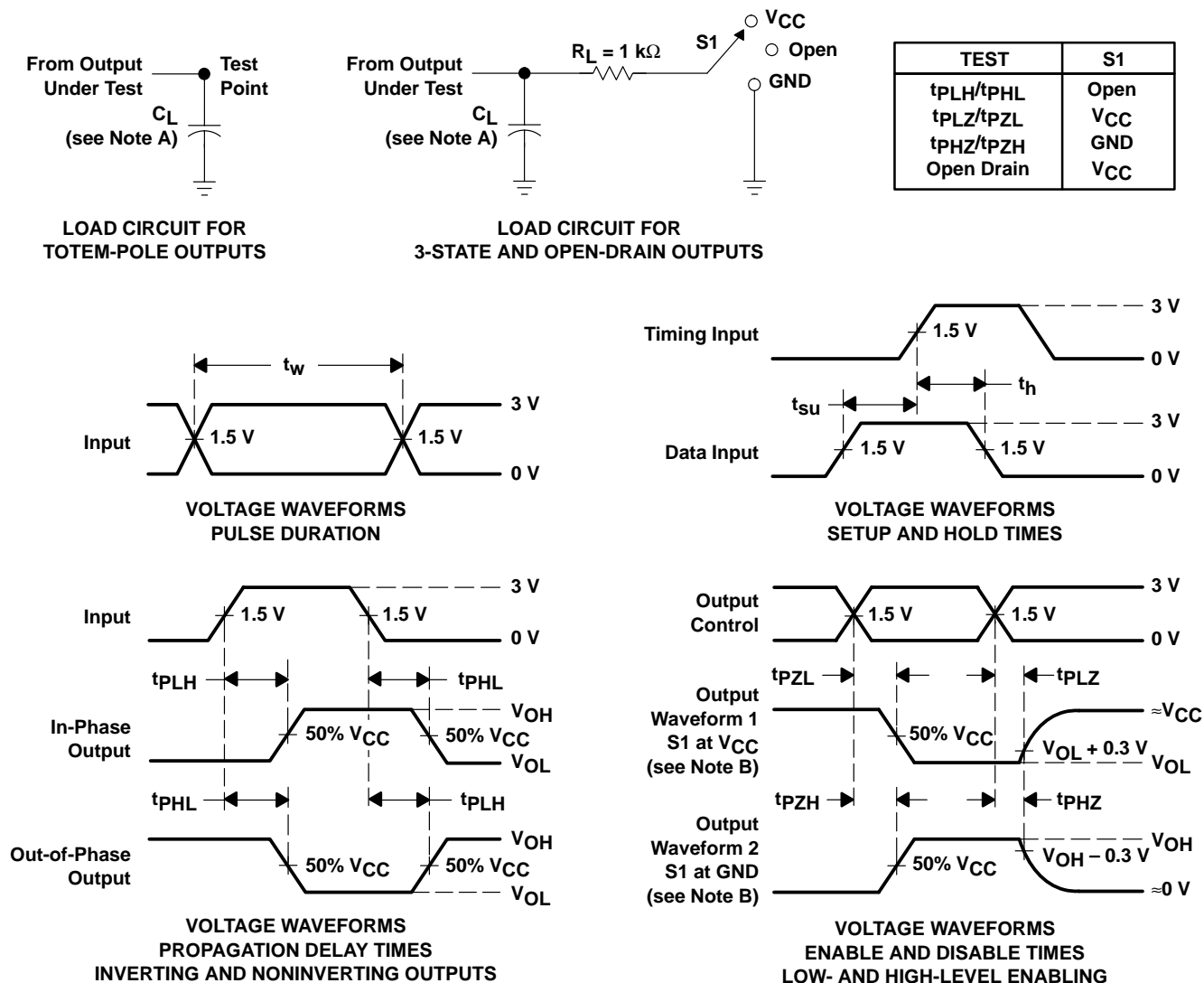| PARAMETER		SN74AHCT125		UNIT
		MIN	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		−0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}	4.4		V
$V_{IH(D)}$	High-level dynamic input voltage	2		V
$V_{IL(D)}$	Low-level dynamic input voltage		0.8	V

NOTE 5:   Characteristics are for surface-mount packages only.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	No load, f = 1 MHz	14	pF

PARAMETER MEASUREMENT INFORMATION

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}

**LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS**

**LOAD CIRCUIT FOR
3-STATE AND OPEN-DRAIN OUTPUTS**

**VOLTAGE WAVEFORMS
PULSE DURATION**

**VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES**

**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS**

**VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING**

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.
E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**TEXAS
INSTRUMENTS**

24-Oct-2005

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
5962-9686901Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-9686901QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9686901QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN74AHCT125D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74AHCT125DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125DGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125DGVRE4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AHCT125NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AHCT125NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125PWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125PWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74AHCT125PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT125RGYR	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74AHCT125RGYRG4	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SNJ54AHCT125FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AHCT125J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AHCT125W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

J (R−GDIP−T**)   CERAMIC DUAL IN−LINE PACKAGE
14 LEADS SHOWN
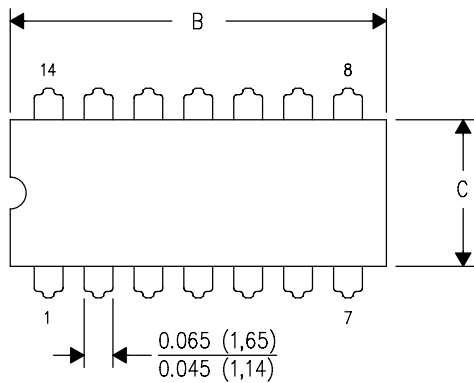
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	——	——	——	——
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

B

14   8

$\frac{0.065\ (1,65)}{0.045\ (1,14)}$

1   7

C

0.005 (0,13) MIN

$\frac{0.060\ (1,52)}{0.015\ (0,38)}$

0.200 (5,08) MAX

Seating Plane

0.130 (3,30) MIN

$\frac{0.026\ (0,66)}{0.014\ (0,36)}$

0.100 (2,54)

A

0°−15°

$\frac{0.014\ (0,36)}{0.008\ (0,20)}$

4040083/F 03/03

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package is hermetically sealed with a ceramic lid using glass frit.
         D.   Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
         E.   Falls within MIL STD 1835 GDIP1−T14, GDIP1−T16, GDIP1−T18 and GDIP1−T20.

W (R−GDFP−F14)   CERAMIC DUAL FLATPACK

0.045 (1,14)
0.026 (0,66)

0.260 (6,60)
0.235 (5,97)

Base and Seating Plane

0.080 (2,03)
0.045 (1,14)

0.006 (0,15)
0.004 (0,10)

0.280 (7,11) MAX

1   14

0.019 (0,48)
0.015 (0,38)

0.050 (1,27)

0.390 (9,91)
0.335 (8,51)

0.005 (0,13) MIN
4 Places

7   8

0.360 (9,14)
0.250 (6,35)

0.360 (9,14)
0.250 (6,35)
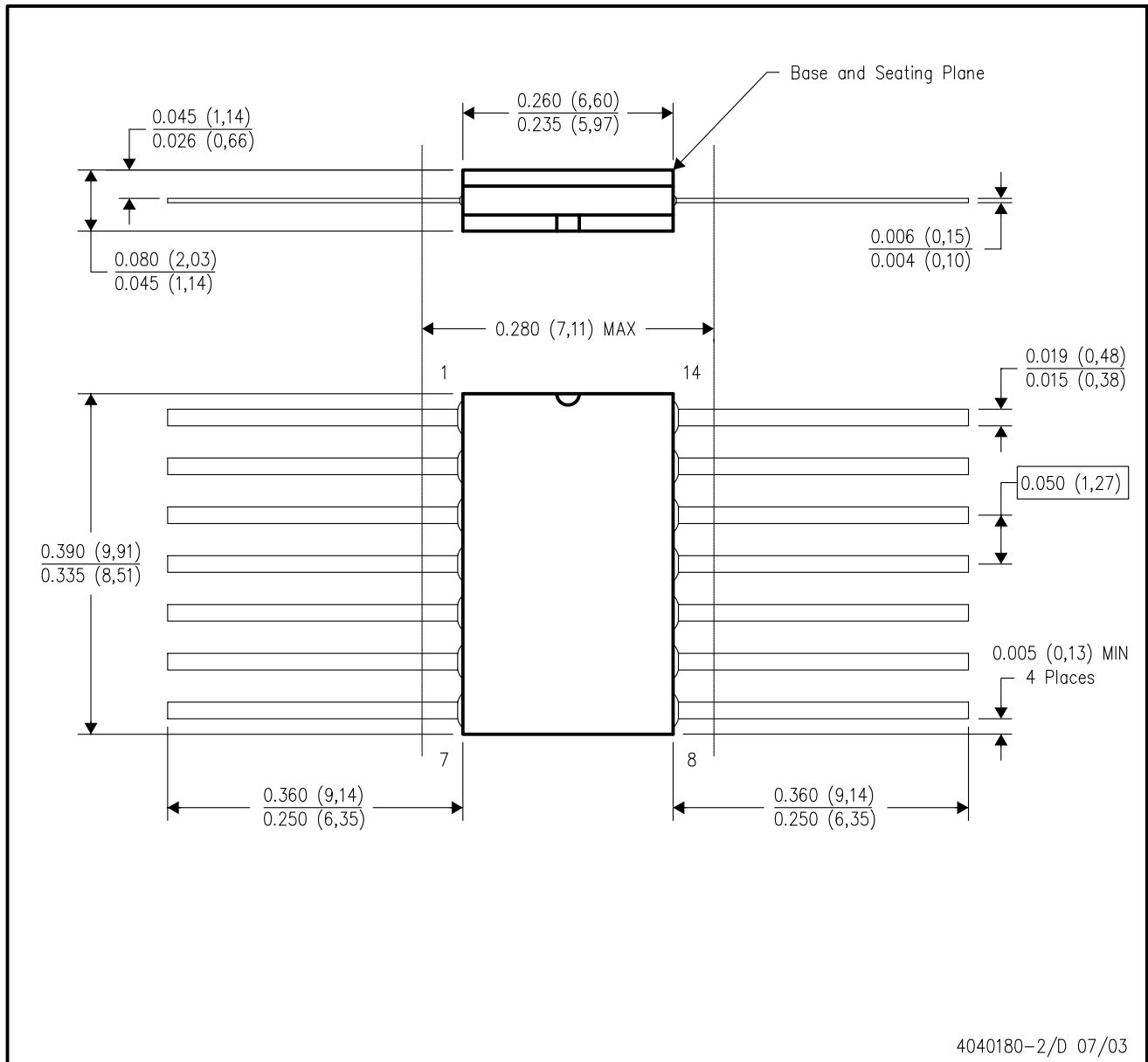
4040180−2/D 07/03

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package can be hermetically sealed with a ceramic lid using glass frit.
         D.   Index point is provided on cap for terminal identification only.
         E.   Falls within MIL STD 1835 GDFP1−F14 and JEDEC MO−092AB

TEXAS
INSTRUMENTS
www.ti.com

MECHANICAL DATA

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER

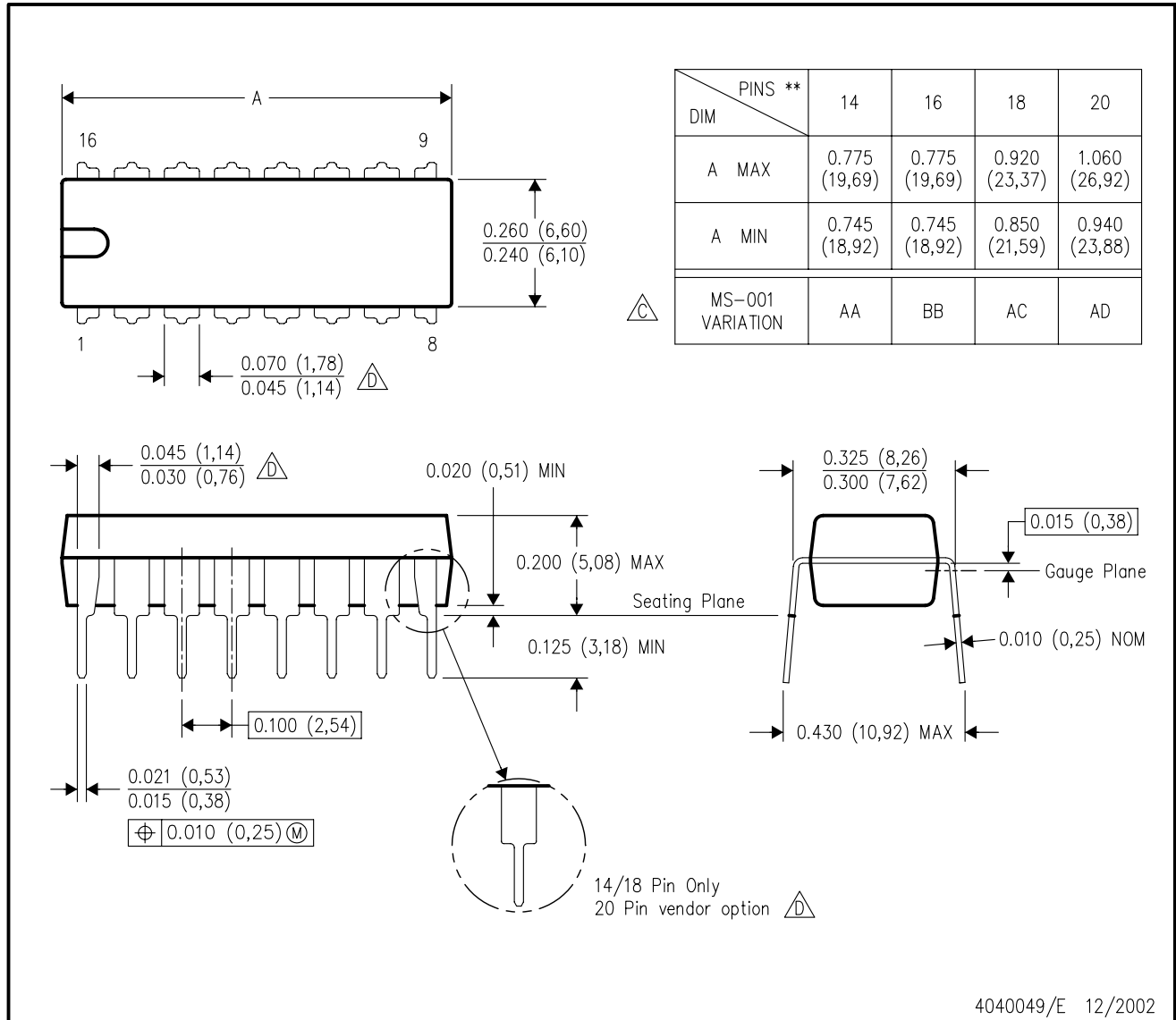| NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

4040140 / D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a metal lid.
 D. The terminals are gold plated.
 E. Falls within JEDEC MS-004

TEXAS INSTRUMENTS

N (R−PDIP−T**)
16 PINS SHOWN

PLASTIC DUAL−IN−LINE PACKAGE

PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS−001 VARIATION	AA	BB	AC	AD

A

16   9

0.260 (6,60)
0.240 (6,10)

1   8

0.070 (1,78)
0.045 (1,14) /D\

0.045 (1,14)
0.030 (0,76) /D\

0.020 (0,51) MIN

0.325 (8,26)
0.300 (7,62)

0.015 (0,38)

0.200 (5,08) MAX

Seating Plane

Gauge Plane

0.125 (3,18) MIN

0.010 (0,25) NOM

0.100 (2,54)

0.021 (0,53)
0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

0.430 (10,92) MAX

14/18 Pin Only
20 Pin vendor option /D\

4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         /C\ Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
         /D\ The 20 pin end lead shoulder width is a vendor option, either half or full width.
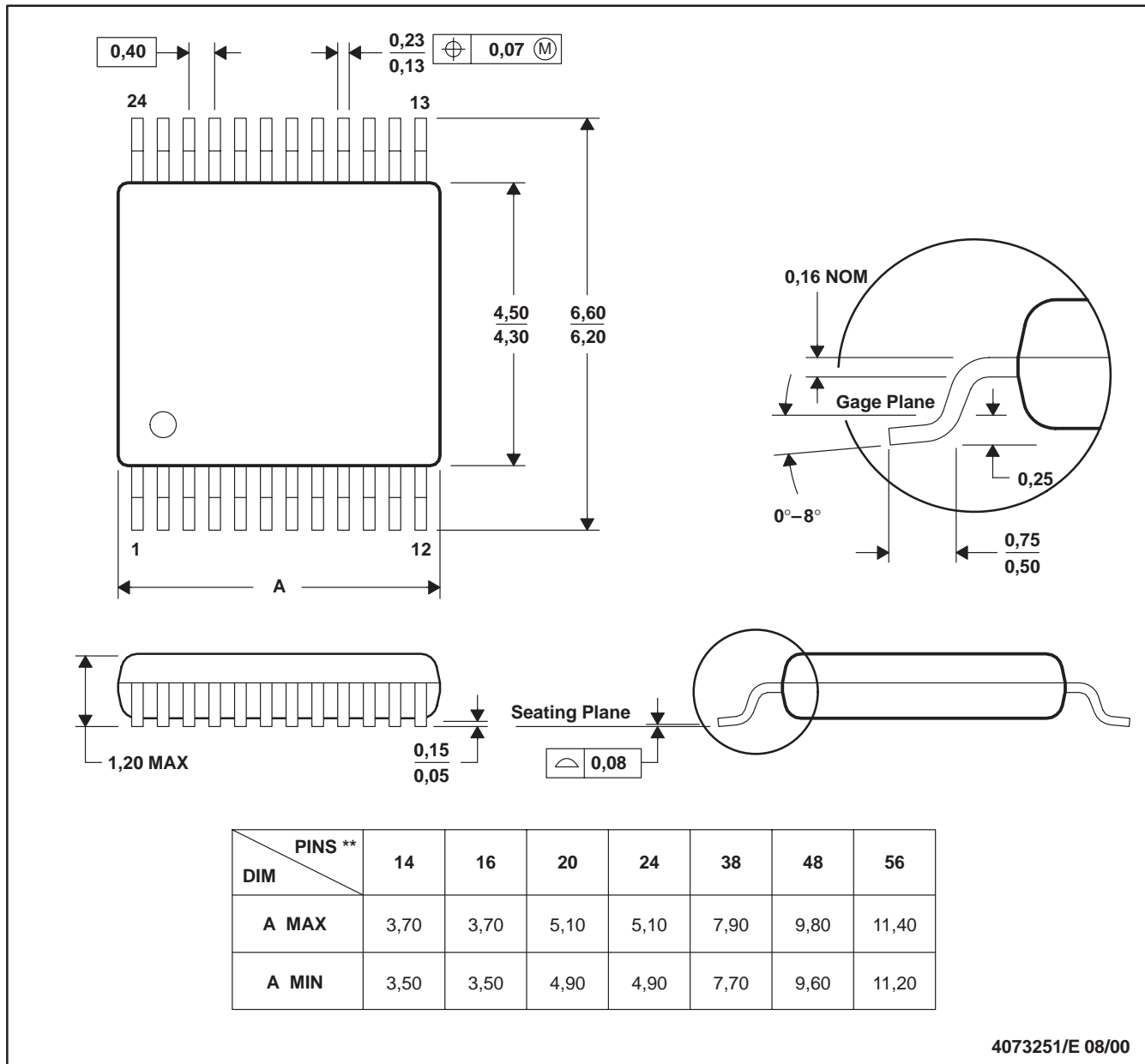
DGV (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE**

24 PINS SHOWN

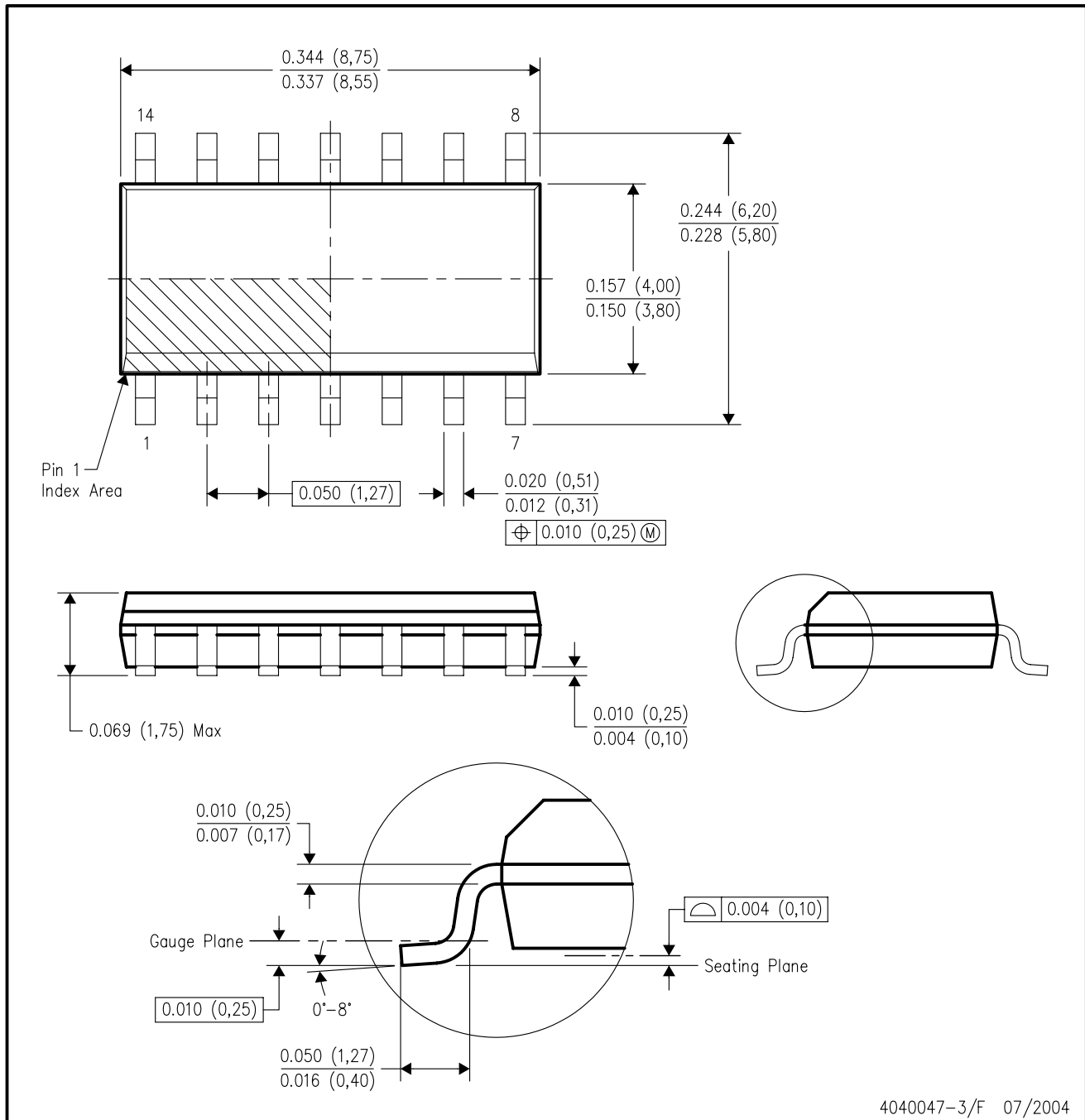| PINS ** DIM	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

NOTES: A. All linear dimensions are in millimeters.
　　　　B. This drawing is subject to change without notice.
　　　　C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
　　　　D. Falls within JEDEC: 24/48 Pins – MO-153
　　　　　　　　　　　　　　　14/16/20/56 Pins – MO-194

TEXAS INSTRUMENTS

D (R−PDSO−G14)   PLASTIC SMALL−OUTLINE PACKAGE

0.344 (8,75)
0.337 (8,55)

14   8

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80)

1   7

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.007 (0,17)

Gauge Plane

◠ 0.004 (0,10)

0.010 (0,25)

0°−8°

Seating Plane

0.050 (1,27)
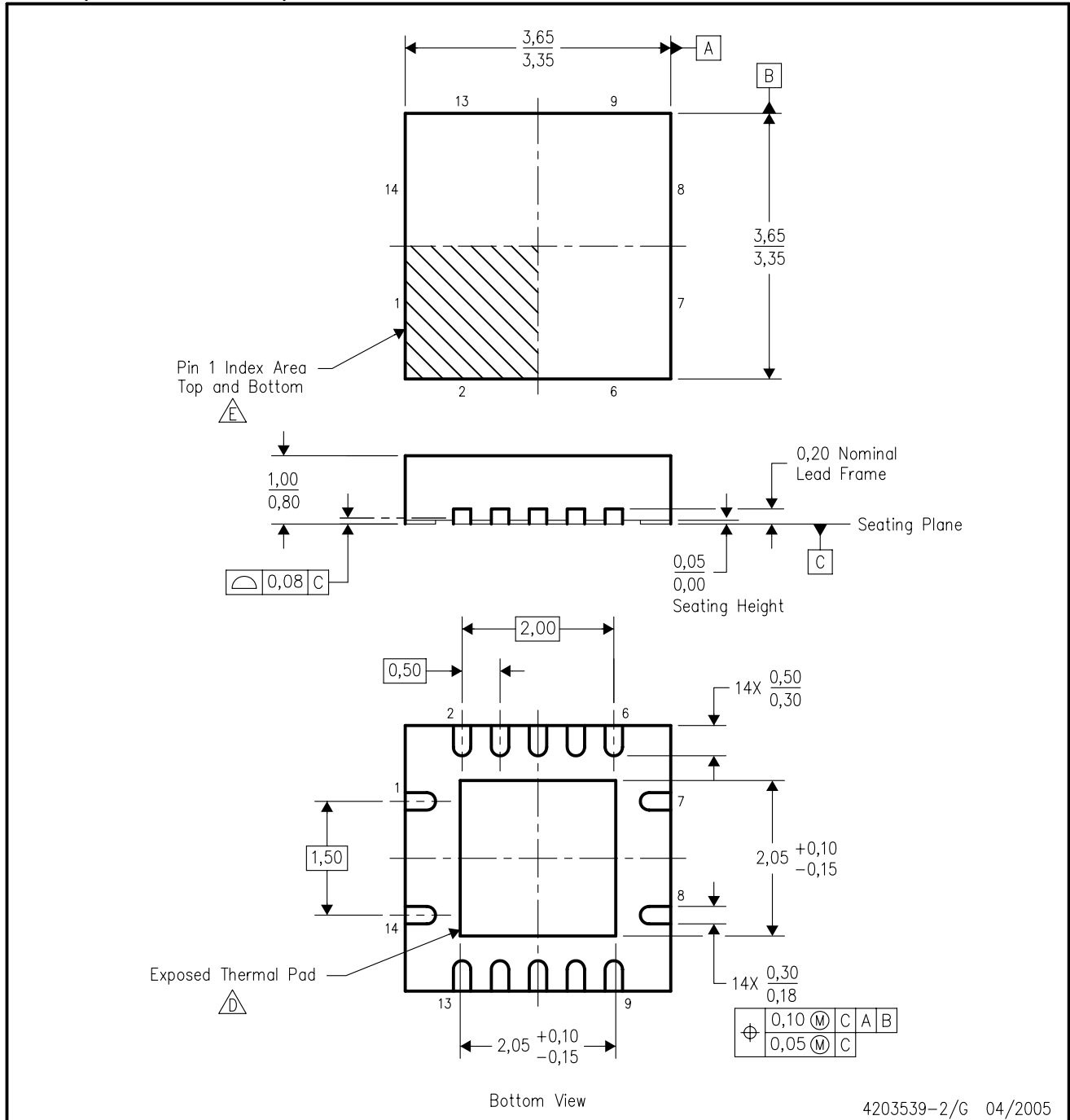0.016 (0,40)

4040047−3/F   07/2004

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
         D.   Falls within JEDEC MS−012 variation AB.

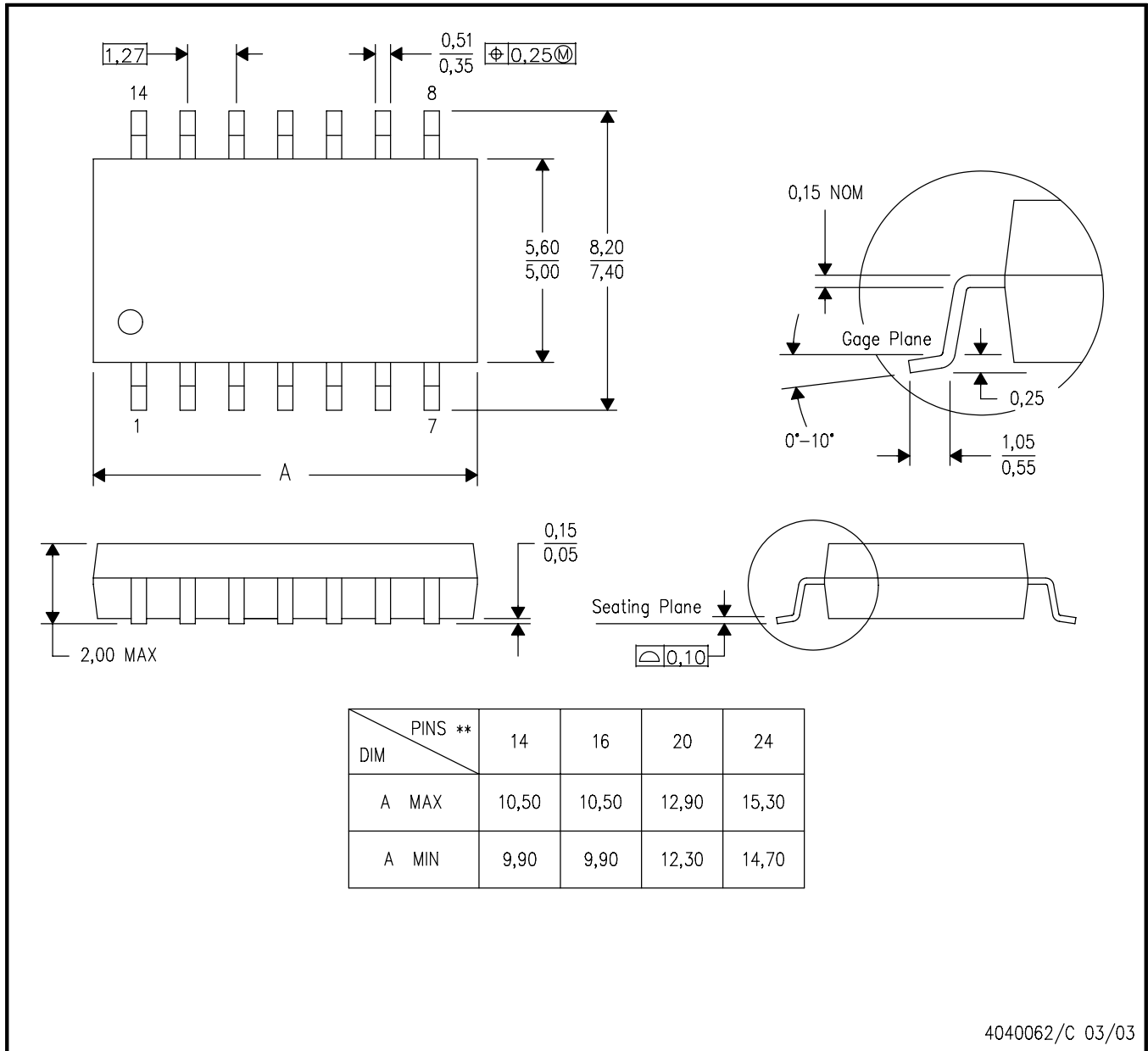## RGY (S−PQFP−N14)   PLASTIC QUAD FLATPACK

3,65 / 3,35 [A]

[B]

13   9

14   8

3,65 / 3,35

1   7

2   6

Pin 1 Index Area
Top and Bottom
[E]

1,00 / 0,80

0,20 Nominal
Lead Frame

Seating Plane

[◠] 0,08 C

0,05 / 0,00
Seating Height

[C]

2,00

0,50

14X 0,50 / 0,30

2   6

1   7

1,50

2,05 +0,10 / −0,15

14   8

Exposed Thermal Pad
[D]

13   9

14X 0,30 / 0,18

2,05 +0,10 / −0,15

| ⊕ | 0,10 Ⓜ | C | A | B |
| | 0,05 Ⓜ | C | | |

Bottom View

4203539−2/G 04/2005

NOTES: A.   All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M−1994.
         B.   This drawing is subject to change without notice.
         C.   QFN (Quad Flatpack No−Lead) package configuration.
      [D]   The package thermal pad must be soldered to the board for thermal and mechanical performance.
      [E]   Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated.
             The Pin 1 identifiers are either a molded, marked, or metal feature.
         F.   Package complies to JEDEC MO−241 variation BA.

MECHANICAL DATA

DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15.
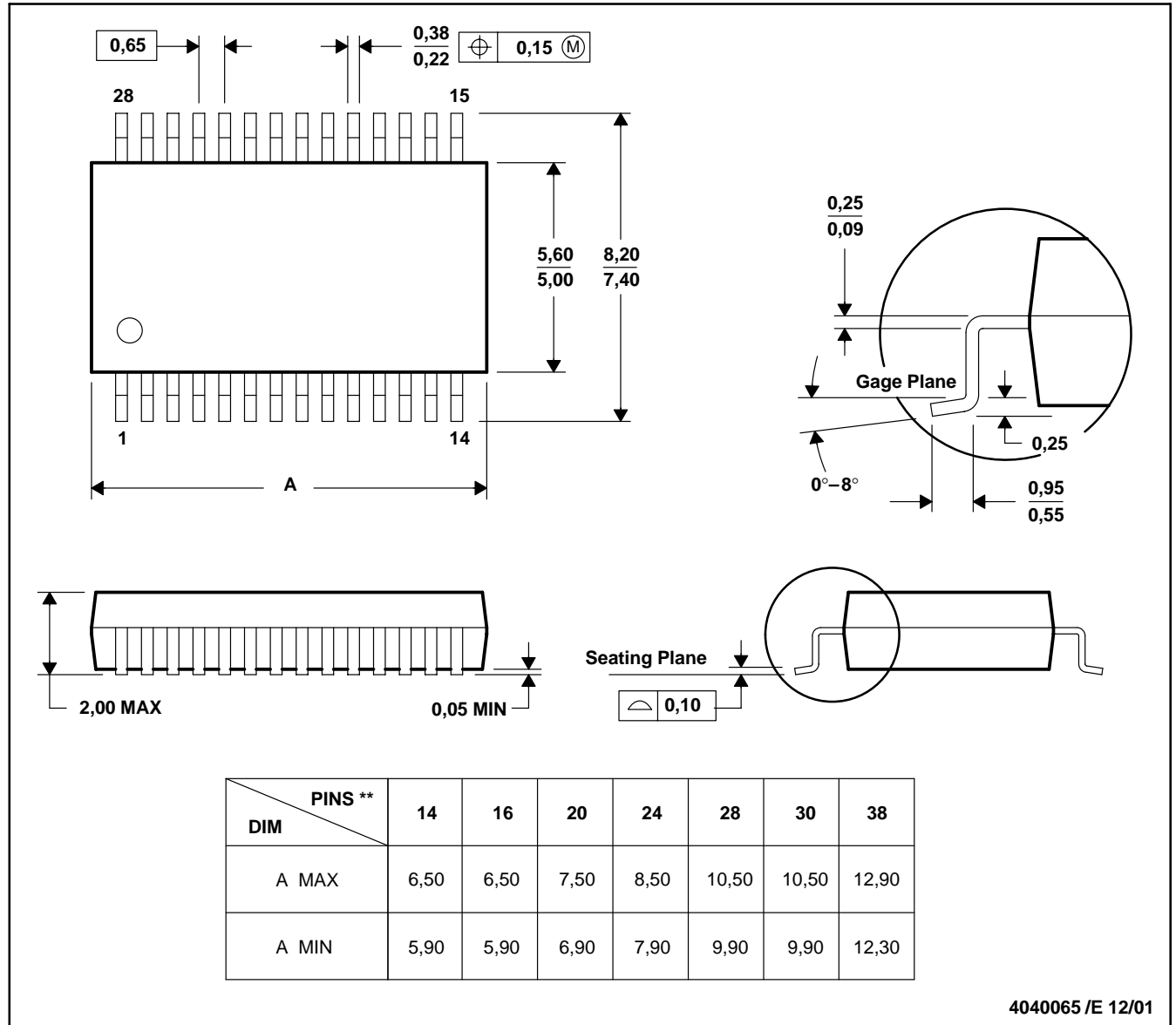
TEXAS
INSTRUMENTS

MECHANICAL DATA

DB (R-PDSO-G**)   PLASTIC SMALL-OUTLINE

28 PINS SHOWN

DIM	PINS **	14	16	20	24	28	30	38
A MAX		6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN		5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
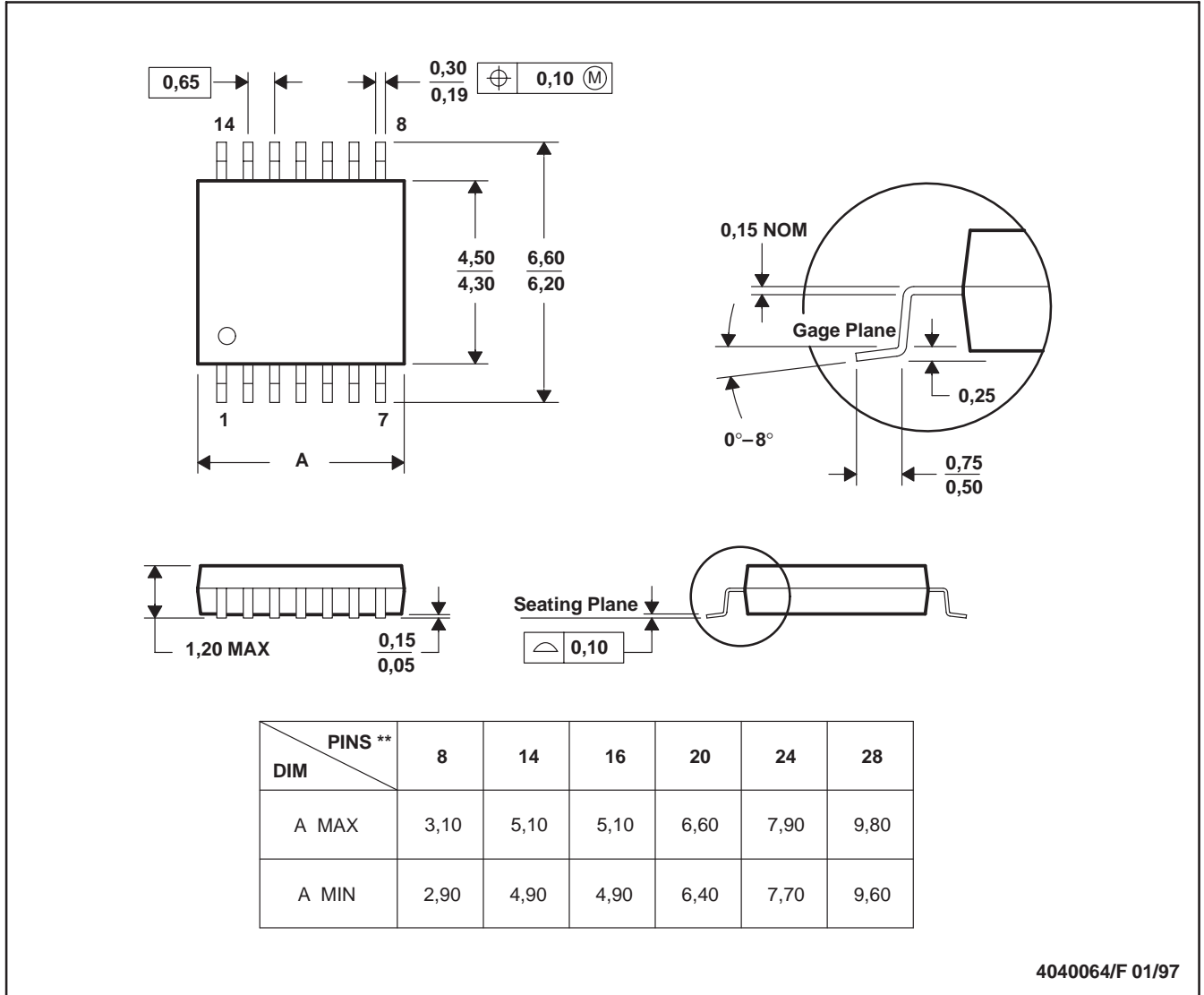D. Falls within JEDEC MO-150

TEXAS INSTRUMENTS

MECHANICAL DATA

PW (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN

	PINS **	8	14	16	20	24	28
DIM							
A MAX		3,10	5,10	5,10	6,60	7,90	9,80
A MIN		2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

TEXAS INSTRUMENTS

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		**Applications**	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
                               Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated